

## B. Claims

The following is a complete listing of the claims, and replaces all earlier versions and listings.

1. (Currently Amended) A solution comprising ionic Fe, ~~ionic Pt a~~ hexachloroplatinate (IV) salt, and tartaric acid as a complex agent at a molar ratio of the ionic Fe to the ~~ionic Pt~~ hexachloroplatinate (IV) salt ranging from 0.75 to 3, and a chloride ion,

wherein the solution is such that it is capable of depositing FePt or FePtCu when plating using the solution is performed,

wherein a concentration of the ionic Fe is from 0.01 mol/L to 0.05 mol/L,

wherein a pH of the solution is from 7.0 to 9.0, and

wherein a chloride ion concentration is not lower than a molar concentration of the hexachloroplatinate (IV) salt.

2-4. (Cancelled)

5. (Currently Amended) The solution according to claim 1, wherein ~~the ionic Fe and the ionic Pt form~~ a double complex constituted of an Fe complex and a Pt complex is formed.

6. (Previously Presented) The solution according to claim 1, wherein the solution contains ionic Cu and a complex agent for the ionic Cu.

7. (Withdrawn) A process for producing a structure comprising steps of:

providing an electrode and an object to be plated in a vessel containing a plating solution set forth in claim 1, and

plating the object with a magnetic material containing FePt from the plating solution by applying voltage to the electrode to form a structure.

8. (Withdrawn) A process for producing a structure, wherein the structure formed in claim 7 is heat-treated further at a temperature ranging from 450°C to 750°C.

9. (Withdrawn) A process for producing a structure, wherein the structure set forth in claim 7 is heat-treated further in the presence of hydrogen.

10. (Withdrawn) The process for producing a structure according to claim 7, wherein the object to be plated is a structure having holes, and the step of plating the object to form the structure is deposition of the magnetic material containing FePt into the holes.

11. (Withdrawn) An apparatus comprising a plating solution as set forth in claim 1, a vessel for holding the plating solution, and electrodes, for conducting plating by application of a voltage to the electrodes.